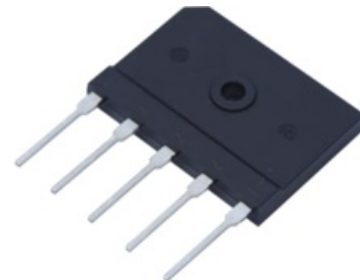


### Three Phase Bridge Rectifier

#### Features

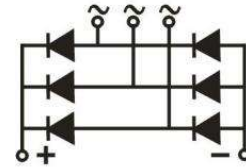
- Glass passivated chip
- Ideal for printed circuit boards
- High surge current capability
- Reverse Voltage : 800 to 1600V
- Forward Current : 15A
- High temperature soldering guaranteed:265°C/10 seconds



**SGBJ**

#### Applications

- Inverter for AC or DC motor control
- Current stabilized power supply
- Input rectifiers for variable frequency drives
- Input rectifiers for PWM inverter



#### Module Type

Type	VRRM	VRSM
SGBJ1508	800V	900V
SGBJ1510	1000V	1100V
SGBJ1512	1200V	1300V
SGBJ1516	1600V	1700V

#### Maximum Ratings

Item	Conditions	Symbol	Values	Unit
Output Current	Three Phase, Full Wave $T_c=110^{\circ}\text{C}$	$I_b$	15	A
Surge Forward Current	$T_j=25^{\circ}\text{C}$ , $t=50\text{Hz}(10\text{ms})$ , $V_R=0\text{V}$	$I_{FSM}$	250	A
Circuit Fusing Consideration	$t=10\text{ms}$ $T_j=25^{\circ}\text{C}$	$I^2t$	312	$\text{A}^2\text{s}$
Isolation Breakdown Voltage	AC 50Hz/60Hz; R.M.S; 1min	$V_{ISO}$	2500	V
Operating Junction Temperature		$T_j$	-40 to +150	$^{\circ}\text{C}$
Storage Temperature		$T_{stg}$	-40 to +125	$^{\circ}\text{C}$
Mounting Torque	(Recommended torque:0.65 N·m)	$M_s$	0.8	N·m
Module (Approximately)		Weight	10	g

**Thermal Characteristics**

Item	Conditions	Symbol	Values	Unit
Thermal Impedance, Max	Junction to Case(Per Total)	$R_{th(j-c)}$	1.2	$^{\circ}C/W$
	Junction to Case(Per Diode)		7.2	$^{\circ}C/W$

**Electrical Characteristics**

Item	Conditions	Symbol	Values			Unit
			Min	Typ	Max	
Forward Voltage Drop, Max	$T_j = 25^{\circ}C, I_F = 7.5A$	$V_{FM}$	-	-	1.18	V
Repetitive Peak Reverse Current, Max	$T_j = 25^{\circ}C, V_R = V_{RRM}$	$I_{RRM}$	-	-	5	$\mu A$
	$T_j = 150^{\circ}C, V_R = V_{RRM}$		-	-	3	mA
Threshold Voltage, for power loss calculation only	$T_j = 125^{\circ}C$	$V_{T0}$	0.75			V
Slope Resistance, for power loss calculation only	$T_j = 125^{\circ}C$	$r_T$	23.5			m $\Omega$

**Ratings and Characteristic Curves ( $T_A=25^{\circ}\text{C}$  unless otherwise noted)**

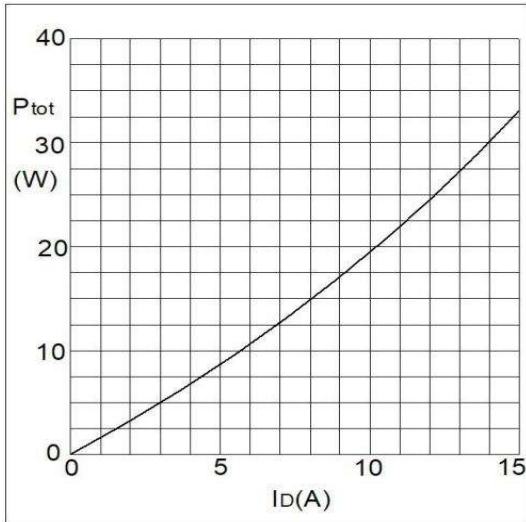


Fig1. Power Dissipation

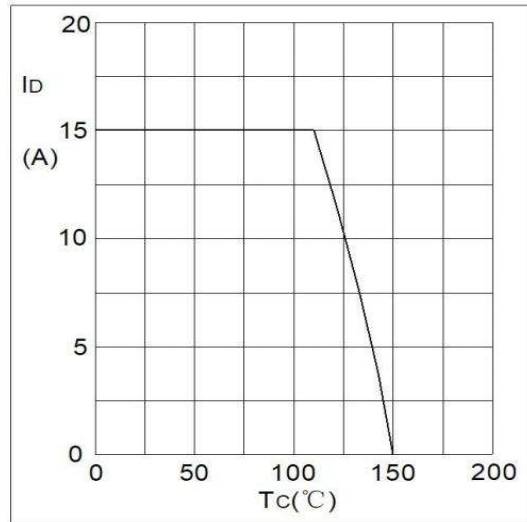


Fig2. Forward Current Derating Curve

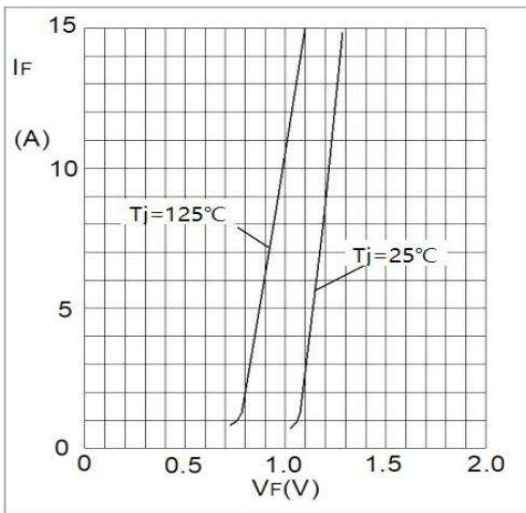


Fig3. Forward Characteristics

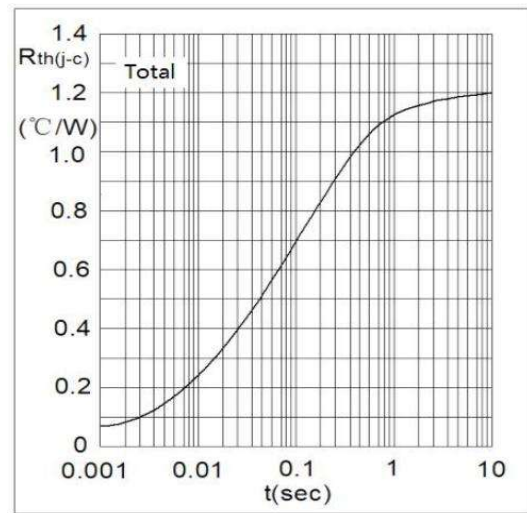


Fig4. Transient Thermal Impedance

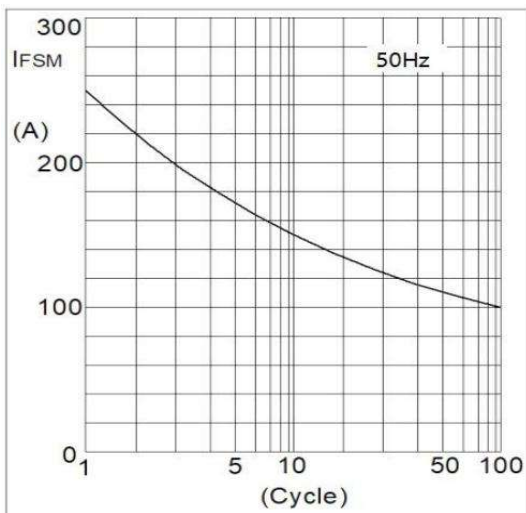
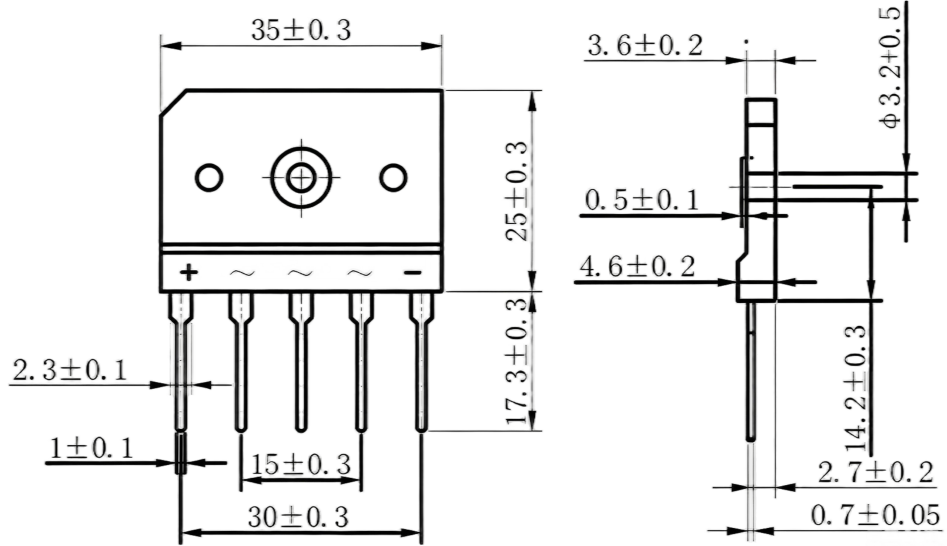


Fig5. Max Non-Repetitive Forward Surge Current

### Package Outlines (Dimensions in mm)

Plastic surface mounted package(SGBJ)



**\*Important Usage Information and Disclaimer**

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